Announcement and Call for Abstracts
Topical Workshop on
3D Applications and Technologies
This workshop is being held as a part of the Device Packaging Conference

WeKoPa Resort & Casino
Fountain Hills, Arizona - USA
March 4 - 7, 2019

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Inho Lee, Dow Electronic Materials

3D Applications and Technologies Workshop Focus:
The objective of this Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of 3D Integration required high density technologies. This workshop has been specifically organized to allow for the presentation and debate of some of the latest advancements in Advanced 3D technologies as well as to bridge the gap between the back-end wafer-level 3D integration and 3D packaging, covering wire-bonded chip stack, interposers, package-on-package (PoP), through-silicon-via (TSV) based die-to-die (or chip), die-to-wafer, and wafer-to-wafer 3D approaches. 3D sessions will also address PCB based packaging approaches, like embedded die, embedded passives and advanced ultra-fine line wiring on substrates for RDL formation.

Abstracts are being requested on the following topics:

3D Technologies and Applications:
- Advanced WB stacking technology
- Advanced PoP technologies
- Advanced Stacked Dies Technology
- Advanced Stacked Packages
- Application for 3D Integration, such as:
  - Stacked Memories, imagers, displays
  - Through Silicon Vias (TSV) Technologies
- Hybrid bonding
- 3D stacking Thermal Management
- Advanced 3D Materials and Processes
- Advanced 3D Testing and Probing Challenges
- Thin Wafer Handling and Processing
- 3D Failure Analysis and Reliability
- 3D Simulation and Modeling
- 3D Applications and System Requirements
- 3D standards
- 3D for AI and HPC (high perform computing)
- EDA & CAD Tools

High Density Interposers
- Technologies for 2.5D
- Silicon & Glass Interposers
- Fine-Line RDL technology
- Advanced Materials and Processes for 2.5D
- 2.5D for graphics modules

Cost Considerations for 2.5 & 3D Packaging
- 3D Embedded Packaging Approaches
  - Laminate embedded die technologies
  - Laminate embedded passives technologies
  - Advanced ultra-fine line wiring on substrates for RDL formation

Those wishing to present in the Device Packaging Conference must submit a ~500 word abstract electronically no later than October 26, 2018, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to four-page “extended abstract” with text (figures and graphs included if necessary) will be required for the abstract booklet on January 31, 2019. Please contact Brian Schieman by email at bschieman@imaps.org if you have questions.

STUDENT AUTHORS: upon abstract submission, please select “yes, I’m a full-time student” on the form and you will automatically be entered in the student competition with $3000 in foundation awards ($1500 1st, $1000 2nd, $500 3rd).

Device Packaging Exhibit and Technology Show:
IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of 3D Applications & Technologies. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8’ by 10’ exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before December 1, 2018 at: www.imaps.org/devicepackaging or contact Brian Schieman by email at bschieman@imaps.org.

Device Packaging Professional Development Courses (PDCs):
For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 4th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course on-line at www.imaps.org/pdc no later than October 26, 2018.